



Description

The HESDLC36VB1AF-A protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN1006-2L

Features

★ IEC 61000-4-2 Level 4 ESD Protection

- $\pm 8\text{kV}$ Contact Discharge
- $\pm 15\text{kV}$ Air Discharge

★ 180W Peak pulse Power (8/20us)

★ Low clamping voltage

★ Working voltage: 36V

★ Low leakage current

★ RoHS compliant

★ Protecting one bi-directional lines



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HESDLC36VB1AF-A	DFN1006-2L	10000

Absolute Ratings(Tamb = 25°C)

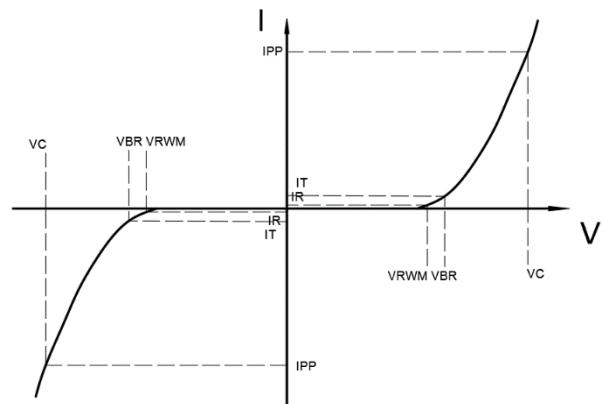
Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	180	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-55 to +150	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	±15 ±8
			KV



Electrical Characteristics Ratings at 25°C

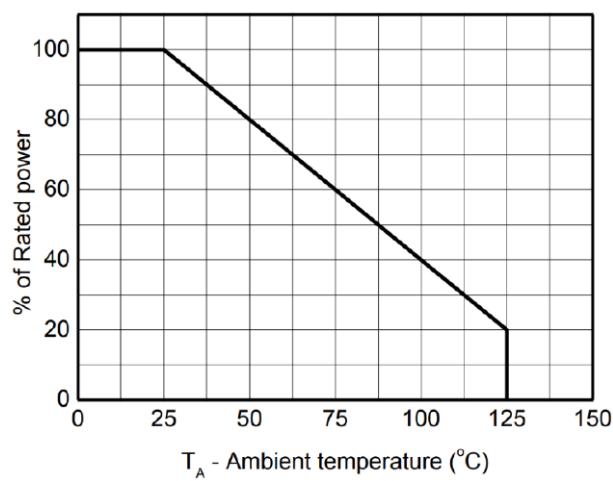
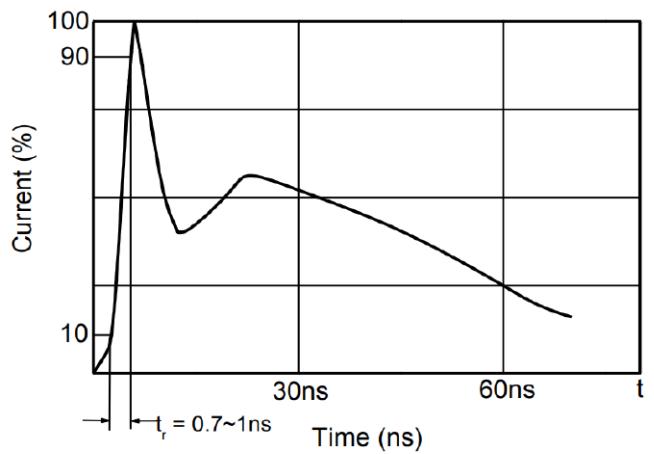
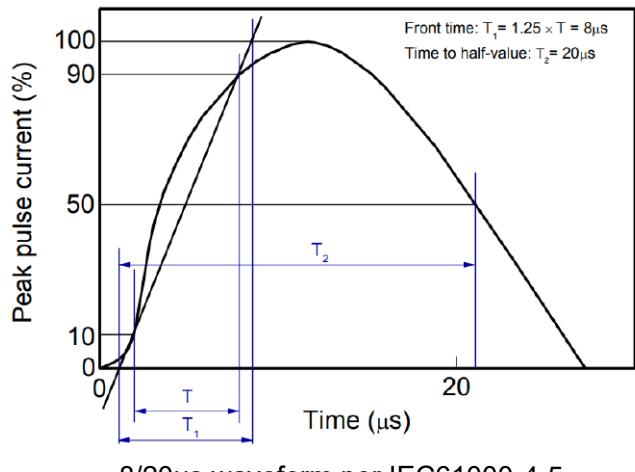
Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				36	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	38			V
I_R	Reverse Leakage Current	$V_{RWM} = 36\text{V}$			1	nA
V_C	Clamping Voltage	$I_{PP} = 1\text{A}, t_p = 8/20\mu\text{s}$		48	58	V
		$I_{PP} = 3\text{A}, t_p = 8/20\mu\text{s}$		55	70	V
C_J	Junction Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$		15	25	pF

Symbol	Parameters
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}

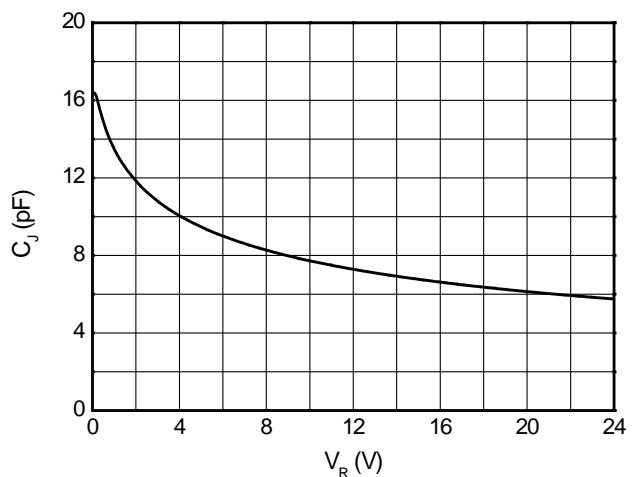




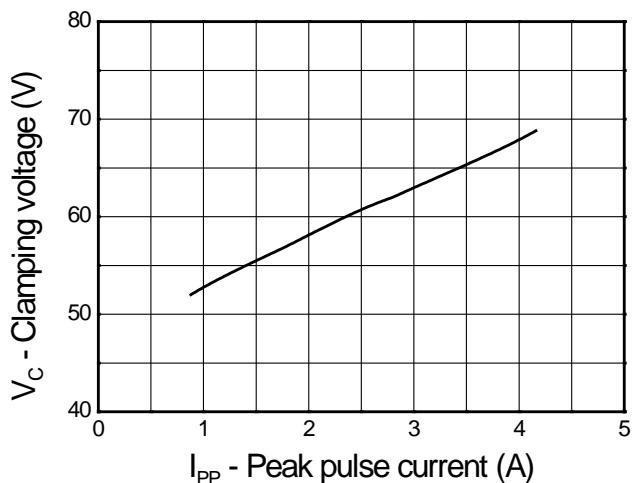
Typical Characteristics



Power derating vs. Ambient temperature



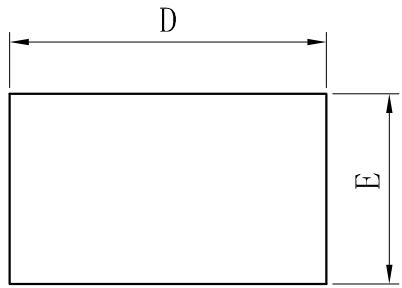
Capacitance vs. Reverse voltage



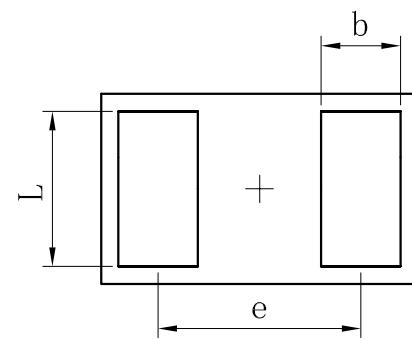
Clamping voltage vs. Peak pulse current



Outline And Dimensions

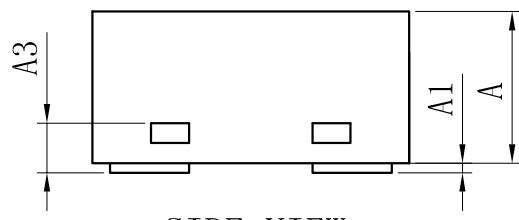


TOP VIEW



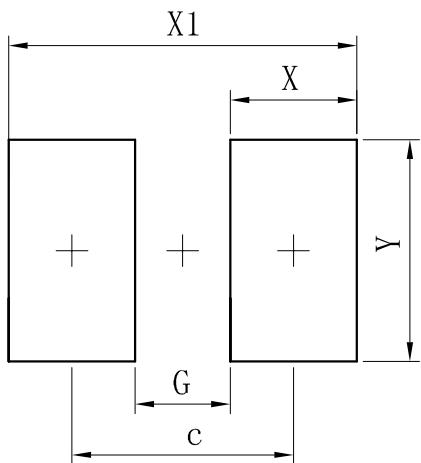
BOTTOM VIEW

DFN1006-2L			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	—	0.64	—
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	—	0.05
A3	0.127REF.		
All Dimensions in mm			



SIDE VIEW

Soldering Footprint



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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